

MMIC

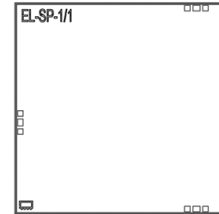
Power Splitter/Combiner Die

EP2RCW-D+

2 Way-0° 50Ω DC to 8 GHz

The Big Deal

- Ultra-Wide Bandwidth, DC to 8 GHz
- High Isolation, 21 dB typ. at 4 GHz
- High Power Handling, 0.6W as a splitter/combiner



Product Overview

Mini-Circuits' EP2RCW-D+ is a MMIC 2-way 0° splitter/combiner Die designed for wideband operation from DC to 8 GHz supporting many applications requiring high performance across a wide frequency range including all the LTE bands through WiMax an WiFi, as well as instrumentation and more. This model provides excellent power handling up to 0.6W (as a splitter/combiner) with low insertion loss, good isolation, and low phase and amplitude unbalance. Manufactured using GaAs IPD technology, the EP2RCW-D+ provides a high level of ESD protection and excellent repeatability.

Key Features

Feature	Advantages
Wideband, DC to 8 GHz	One power splitter can be used in all the LTE bands through WiMAX and WiFi, saving component count. Also ideal for wideband applications such as military and instrumentation.
Excellent power handling <ul style="list-style-type: none">• 0.6W as a splitter• 0.6W internal dissipation as a combiner	In power combiner applications, half the power is dissipated internally. EP2RCW-D+ is designed to handle 0.6W internal dissipation as a combiner allowing reliable operation without excessive temperature rise.
Unpackaged Die	Enables user to integrate it directly into hybrids.



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Product Features

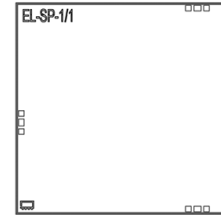
- Wide bandwidth, DC to 8 GHz
- Excellent isolation, 21 dB typ. up to 4 GHz
- Excellent amplitude unbalance, 0.1 dB typ. up to 8 GHz
- Good phase unbalance, 0.1 deg. typ. at 4 GHz
- High ESD level
- Patent pending

Typical Applications

- WIMAX
- ISM
- Instrumentation
- Radar
- WLAN
- Satellite communications
- LTE

General Description

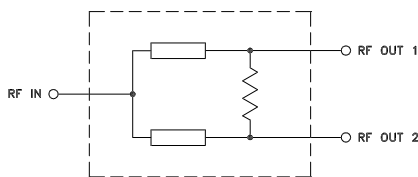
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+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

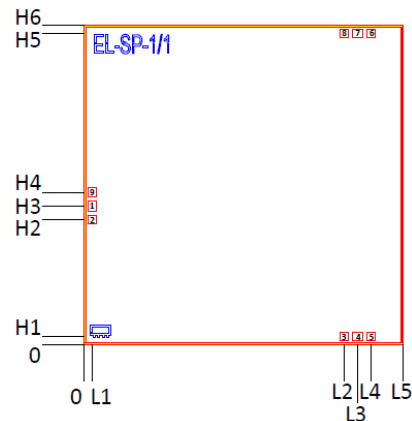
Simplified Schematic and Pad Description



Pad#	Function
1	Sum Port (RF IN)
4	Port 1 (RF OUT 1)
7	Port 2 (RF OUT 2)
2,3,5,6,8,9	Ground

Note: 1. Bond Pad material - Gold
2. Bottom of Die is ground - Gold plated

Bonding Pad Position



L1	L2	L3	L4	L5	H1	H2	H3	H4	H5	H6	Thickness	Die Size	Pad Size	Pad Size 2,3,5,6,8,9	Pad Size 7&4
89	2851	3001	3151	3500	88	1370	1520	1670	3412	3500	100	3500x3500	92x117	92x92	117x92



Electrical Specifications at 25°C¹

Parameter	Frequency (GHz)	Min.	Typ.	Max.	Unit
Frequency Range		DC		8	GHz
Insertion Loss, above 3.0 dB	DC - 0.4	—	5.4	—	dB
	0.4 - 0.7	—	5.4	—	
	0.7 - 7.5	—	4.5	—	
	7.5 - 8.0	—	3.7	—	
Isolation	DC - 0.4	—	16.9	—	dB
	0.4 - 0.7	—	19.3	—	
	0.7 - 7.5	—	22.3	—	
	7.5 - 8.0	—	21.9	—	
Phase Unbalance	DC - 0.4	—	0.1	—	Degree
	0.4 - 0.7	—	0.1	—	
	0.7 - 7.5	—	0.1	—	
	7.5 - 8.0	—	0.2	—	
Amplitude Unbalance	DC - 0.4	—	0.1	—	dB
	0.4 - 0.7	—	0.1	—	
	0.7 - 7.5	—	0.1	—	
	7.5 - 8.0	—	0.1	—	
VSWR (Port S)	DC - 0.4	—	1.1	—	:1
	0.4 - 0.7	—	1.1	—	
	0.7 - 7.5	—	1.6	—	
	7.5 - 8.0	—	1.3	—	
VSWR (Port 1-2)	DC - 0.4	—	1.6	—	:1
	0.4 - 0.7	—	1.8	—	
	0.7 - 7.5	—	1.7	—	
	7.5 - 8.0	—	1.2	—	
Power Handling	As a splitter	DC - 8	—	0.6	W
	As a combiner	DC - 8	—	0.6	

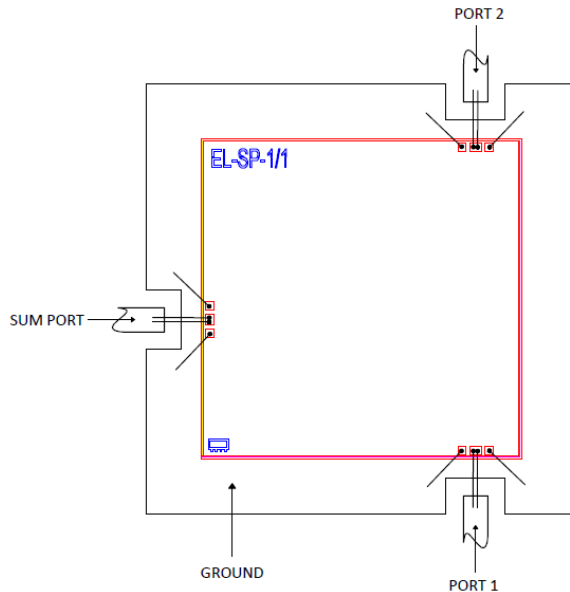
1. Measured on die using MPI Titan series 150 µm pitch as probe

Maximum Ratings

Parameter	Ratings
Operating Temperature	-55°C to 105°C

Permanent damage may occur if any of these limits are exceeded.

Assembly Diagram



Assembly and Handling Procedure

1. Storage
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
MMIC dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
The Die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total Die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic Die pick up tools only.
4. Wire Bonding
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the Die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

Additional Detailed Technical Information <i>additional information is available on our dash board.</i>							
Performance Data	Data Table						
	Swept Graphs						
	S-Parameter (S3P Files) Data Set with and without port extension(.zip file)						
Case Style	Die						
Die Ordering and packaging information	<table> <tr> <td>Quantity, Package</td> <td>Model No.</td> </tr> <tr> <td>Small, Gel - Pak: 5,10</td> <td>EP2RCW-DG+</td> </tr> <tr> <td>Medium†, Partial wafer: 225 Max.</td> <td>EP2RCW-DP+</td> </tr> </table> <p>†Available upon request contact sales representative</p> <p>Refer to AN-60-067</p>	Quantity, Package	Model No.	Small, Gel - Pak: 5,10	EP2RCW-DG+	Medium†, Partial wafer: 225 Max.	EP2RCW-DP+
Quantity, Package	Model No.						
Small, Gel - Pak: 5,10	EP2RCW-DG+						
Medium†, Partial wafer: 225 Max.	EP2RCW-DP+						
Environmental Ratings	ENV-80						

ESD Rating**

Human Body Model (HBM): Class 2 (Pass 2000V) in accordance with ANSI/ESD STM 5.1 - 2001

** Tested in industry standard, 5x5mm, 32-lead MCLP package.

Additional Notes

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